ABSTRACT OF THE DISCLOSURE

SUBSTRATE POLISHING APPARATUS AND SUBSTRATE POLISHING METHOD

The substrate polishing apparatus capable of measuring a film thickness of a substrate with high accuracy without decreasing a transmittance of light when measuring the film thickness of a substrate being polished is disclosed. The substrate polishing apparatus includes: a stage; a polishing head configured to hold a polishing pad; a polishing-liquid supply nozzle; a film-thickness measuring head; a spectrum analyzer; and a head nozzle to which the film-thickness measuring head is attached. The head nozzle includes a first flow-passage system and a second flow-passage system each configured to form a flow of liquid across an optical path of light and reflected light, the first flow-passage system has an aperture located on the optical path, the second flow-passage system has a liquid outlet port and a liquid suction port located at both sides of the aperture.

FIG. 6